AMOLED Manufacturing Process Report

Ver. 4

2022





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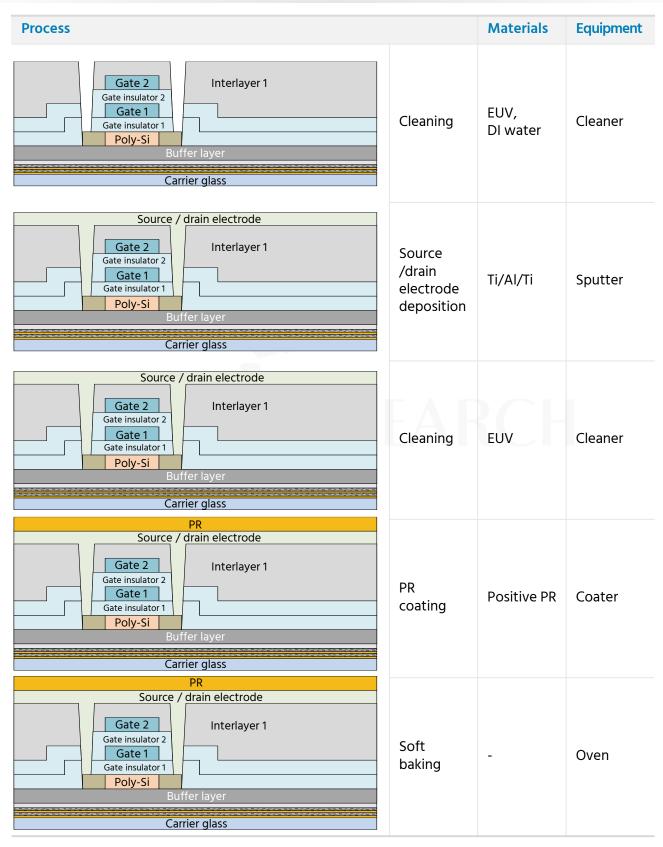
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2. TFT Manufacturing Process

2.3 SDC LTPS TFT Manufacturing Process

· Source/drain electrode 1 deposition

LTPS TFT manufacturing process and equipment



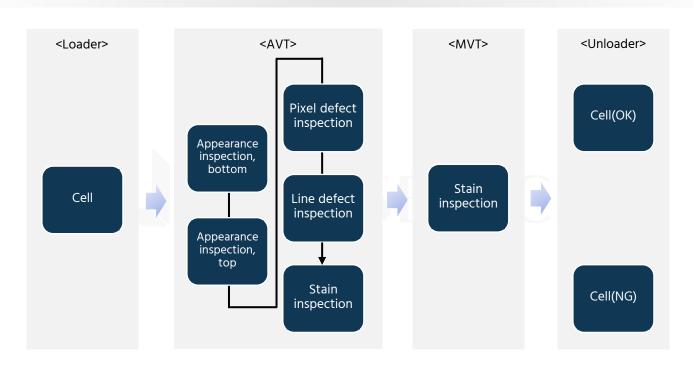
4. Cell Manufacturing Process

4.5 Cell Inspection and Measurement Process

AVT/MVT equipment

- · AVT(auto vision tester) equipment is used to inspect the top and bottom of the OLED cell to check for defects such as scratches and cracks, and then to check for stain, pixel defect, line defect, etc.
- · MVT(manual vision tester) equipment is used to inspect OLED cell to check for defects such as stains after AVT process.

Process of AVI and MVI, details

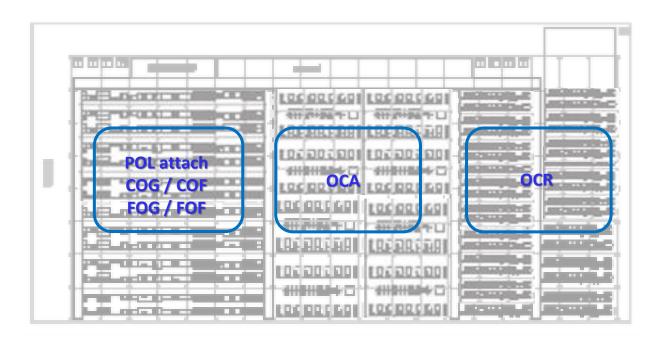


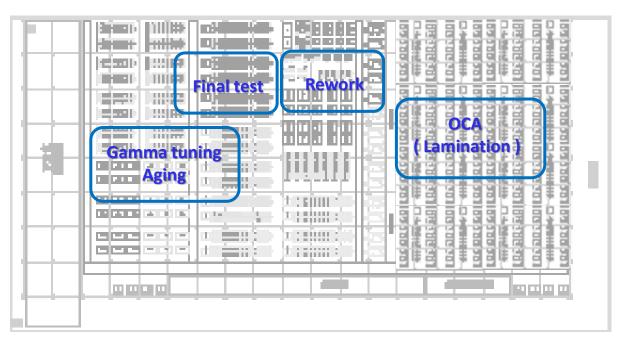
Equipment	Inspection	Details		
	Appearance inspection, bottom	Check for defects such as scratches and cracks		
	Appearance inspection, top	check for defects such as scratches and cracks		
AVT	Stain inspection	Automatic stain test		
	Pixel defect inspection	Specific pixel defect test such as LD (line defect) and PD (point defect)		
	Line defect inspection	Test for Line open/short		
MVT	Stain inspection	Manual stain test		

5. Module Manufacturing Process

5.1 Module Manufacturing Equipment Layout

Module layout example





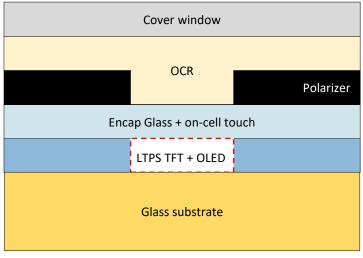
5. Module Manufacturing Process

5.4 Camera Punch Hole Manufacturing Process

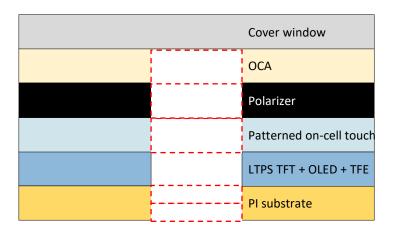
Basic structure

- · Punch hole structure of rigid OLED is a structure like (a) that can pass light by eliminating TFT, emitting layer and electrode layer by laser drilling in vacuum environment after deposition of OLED.
- · Camera punch hole of Flexible OLED removes all of PI substrate to OCA (b).
- · The polarizer for rigid OLED is attached with hole formed, and for flexible OLED, hole is formed by laser









(b) Flexible device structure

6. Apple Watch 5 LTPO TFT Manufacturing Process

6.2 Manufacturing Process

· Ion doping and interlayer 1 deposition

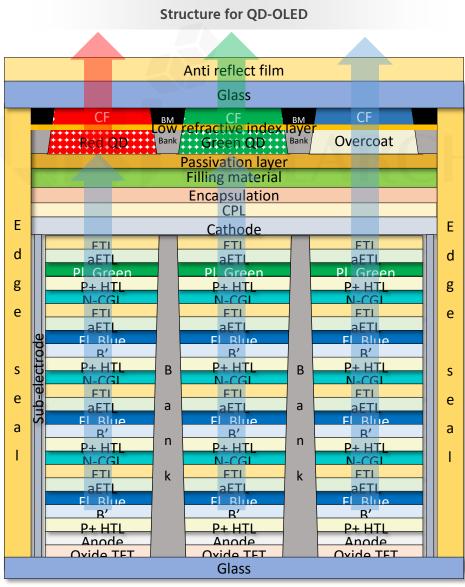
LTPO TFT manufacturing process and equipment

Process		Materials	Equipment
Gl Poly-Si Insulator I/S Carrier glass	lon doping (n+ or p+)	_	lon implanter
p+ or n+ Doping Gate Poly-Si Insulator L/S Carrier glass	Activation	-	RTA or furnace
Gl Poly-Si Insulator L/S Carrier glass	Cleaning	EUV, HF, O ₃ , H ₂ , DI water	Cleaner
ILD Gate GI Poly-Si Insulator L/S Carrier glass	Interlayer deposition	SiNx	PECVD

7. QD-OLED Manufacturing Process

7.1 Expected Structure

- · Oxide TFT is used, and OLED pixel is a 4 stack structure with top emission structure.
- · A color filter is applied initially to prevent the emission of QD material caused by external incident light.
- · A low refractive index layer is added between the color filter and QD to improve light extraction.
- There is no polarize, and an anti-reflect film is applied to the upper substrate to prevent reflection of external light.



Source: UBI Research DB

8. Galaxy Note21 Ultra HOP(LTPO) TFT Manufacturing Process

8.2 Manufacturing Process

· Buffer & LTPS precursor layer deposition

HOP(LTPO) TFT Manufacturing Process and equipment

Process		Materials	Equipment
PI Carrier glass	Cleaning	EUV, DI water	Cleaner
Buffer layer PI Carrier glass	Buffer layer deposition	SiNx/SiOx 500/3000Å	PECVD
BSL Buffer layer PI Carrier glass	a-Si precursor deposition	a-Si 500Å	PECVD
BSL Buffer layer PI Carrier glass	Cleaning	EUV	Cleaner
H ¹ H ² H ³ H ⁴	Dehydrogenat ion	-	Furnace

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